

ABSTRACT OF THE DISCLOSURE

In a provided semiconductor device, a plurality of seal rings each made of a conductive material is formed along a periphery of the semiconductor chip and as to surround the circuit formation portion, the seal rings being connected with the semiconductor substrate and being buried in the plurality of wiring insulating films in such a manner as to extend over the wiring insulating films, and one or more slit-like notches are formed at specified positions in the plurality of seal rings in such a manner that the respective slit-like notches in two seal rings being adjacent to each other are not aligned.